





Power Cycling with the latest generation IGBT die

The Dynex manufacturing plant is a vertically integrated facility with device design, wafer fab, packaging, qualification and testing available on site.

Through initial concept to full production, Dynex support your requirements to provide enhanced, reliable device outlines to meet your specific demands.

Using our in-house design team, Dynex continue to develop processes and designs to utilise the latest techniques to improve cooling, current output, lifetime and reliability.

Great emphasis is placed on low inductance power bus bar designs, enabling the modules to function under fast switching transients such as, those of next generation Trench Gate IGBT's and SiC MOSFET.

Key Features

- High DC stability via advanced edge termination design and passivation
- High short circuit capability-
- wide SCSOA
- Self-limiting short circuit current
- Temperature conditions from -40/-50°C up to +150°C
- Low switching losses
- T(vj op) = 150°C
- AlSiC Baseplate for increased thermal cycling capability
- Package design with CTI > 600
- Isolated base plate
- 400A to 3600A at 750V to 6500V

Applications

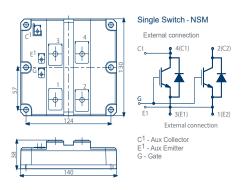
- High reliability inverters
- Motor controllers
- Traction drives
- Different circuit topologies (half bridge, single switch, chopper)

IMPORTANT INFORMATION: The products and information in this publication are intended for use by appropriately trained technical personnel. Due to the diversity of product applications, the information contained herein is provided as a general guide only and does not constitute any guarantee of suitability for use in a specific application. The user must evaluate the suitability of the product and the completenessofthe productdata for the application. The user is responsible for product selection and ensuring all safety and any warning requirements are met. Although we have endeavoured to carefully compile the information in this publication it may contain inaccuracies or typographical errors. The information is provided without any warranty or guarantee of any kind. This publication is an uncontrolled document and is subject to change without notice. When referring to it please ensure that it is the most up to date version and has not been superseded. The products are not intended for use in medical or other applications where a failure ormal function may cause loss of life, injury or damage to property. The user must ensure that appropriates afety precautions are taken to preventor mitigate the consequences of aproduct failure ormal function. All products and materials are sold and services provided subject to Dynex's conditions of sale, which are available on request. Any brand names and product names used in this publication are trademarks, registered trademarks or tradenames of their respective owners. Warning: Counterfeit Products - There are counterfeit products on the market place which closely resemble Dynex's genuine products. Dynex does not support the sale of products of uncontended for use in the sale of products of uncontended for use in the sale of products of uncontended for use in the sale of th

y (in)

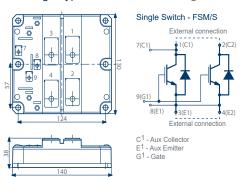


Package Type: N Nominal weight: 1000g

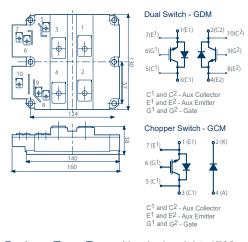


Package Type: F

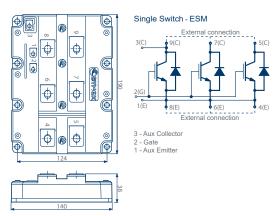
Nominal weight: 1000g/ 1600g



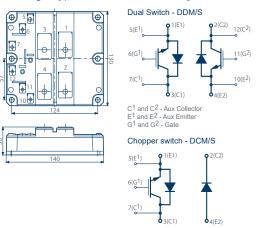
Package Type: G Nominal weight: 1000g



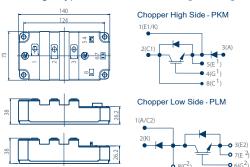
Package Type: E Nominal weight: 1700g



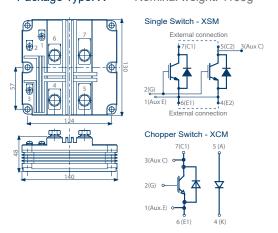
Package Type: D Nominal weight: 1000/ 1600g



Package Type: P Nominal weight: 500g



Package Type: X Nominal weight: 1100g



Package Type: A Nominal weight: 1700g

